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PATENT

UNITED STATES DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

Applicant: Sasazaki, Tatsuo)	Priority: PCT/JP2005/005475
)	
Serial No: 10/593,932)	GROUP ART UNIT: Unk
)	
Filing Date: 9/21/2006)	EXAMINER: UNK
Title:)	
SHEET-LIKE FORMED)	KIYO-48
MATERIAL)	
)	Fax: 571 273 8300
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Commissioner for Patents		
P.O. Box 1450		
Alexandria, VA 22313-1450		

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Pursuant to 37 CFR section 1.97, the Applicant submits the following information, accompanied by a copy of the cited documents. Form PTO 1449 is attached. A detailed discussion will follow.

By submitting these materials, the applicant does not concede that all are prior art. They do not know when some of the competitive devices were first made public. These references were recently provided by the applicant's Japan Patent Attorney.

Introduction:

The inventor of the invention set forth in the application identified in the heading of this document is an individual. The inventors have participated in the design and development of the invention.

Some of the references appear to be relevant to, or useful in, evaluating the present patent application. For the purpose of completeness and accuracy, this patents are enclosed.

References:

U.S. Patents

1. U.S. Patent No. 6,478,229 to Epstein which issued on November 12, 2002 and entitled "PACKAGING TAPE WITH RADIO FREQUENCY IDENTIFICATION TECHNOLOGY" discloses the making of tags on a roll using adhesive packaging.

2. U.S. Patent No. 6,667,092 to Brollier et al, which issued on December 23, 2003, and entitled "RFID ENABLED CORRUGATED STRUCTURES" discloses structures in which components displace part of the corrugation.

Foreign References

1. Japan Patent Reference JP 2002-319006 of 2002/10/31 and entitled "ANTI-COUNTERFEIT THREAD, ANTI-COUNTERFEIT SHEET-SHAPED MATERIAL USING IT, AND METHOD OF MANUFACTURING IT, and discloses a method of inserting fine semiconductor chips on a sheet.
2. Japan Patent Reference JP 2003-011914 of 2003/01/15 and entitled "METHOD FOR MOUNTING ic TAG AND CARRIER TAPE FOR FEEDING IC TAG, and discloses a machine process for mounting an IC tag on an article.
3. Japan Patent Reference JP 2003-081344 of 2003/03/19 and entitled "AUXILIARY PACKAGING MATERIAL ON WHICH IC IS FITTED, and discloses a method of affixing an IC, even after the contents of a packaging have been added.
4. Japan Patent Reference JP 2003-216984 of 2003/07/31 and entitled "TICKED ISSUING TERMINAL EQUIPMENT FOR ROLLED PAPER, AND CONTROL SYSTEM, and discloses a method of controlling tickets one by one.
5. Japan Patent Reference JP 2003-233311 of 2003/08/22 and entitled "CONTINUOUS BODY OF LABEL AND METHOD OF

MANUFACTURING THE SAME, and discloses a method of label making by cutting the functions parts from a sheet.

6. Japan Patent Reference JP 2003-281630 of 2003/10/03 and entitled "RECEIPT AND REGISTER FOR ISSUING IT, and discloses a method of input information for transfer of money.
7. Japan Patent Reference JP 2005-084954 of 2005/03/31 and entitled "ELECTRONIC TAG-MOUNTED COMBINATIONAL DEVICE AND ELECTRONIC TAG, and discloses a method of mounting a tag on an article.
8. Japan Patent Reference JP 2006-306977 of 2006/11/09 and entitled "MANUFACTURING METHOD OF CORRUGATED CARDBOARD WITH IC INLET, and discloses a method of manufacturing corrugated cardboard without using tear tape.

RECEIPT WITHOUT FEE DUE

This disclosure statement should be received without fee because:

XXXX Under 37 CFR 1.97 (b) this information disclosure statement is filed: (1) within three months of

the filing date of a national application; or (2) Within three months of the date of entry of the national stage as set forth in w 1.491 in an international application; or (3) Before the mailing date of a first Office action on the merits.

N/A Certification

Attorney for Applicant Certifies that:

_____ (0) This disclosure statement is being filed with the patent application.

_____ (1) That each item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the statement, (facts outlined above) or

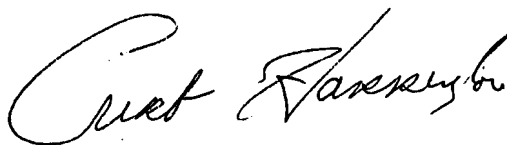
_____ (2) That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the person signing the certification after making reasonable inquiry, was known to any individual designated in # 1.56(c) more than three months prior to the filing of the statement.

(Cited in related U.S. Application)

For the foregoing reasons, the Applicants submits that these references neither disclose nor suggest the claimed invention.

Dated: May 29, 2007

Respectfully submitted:



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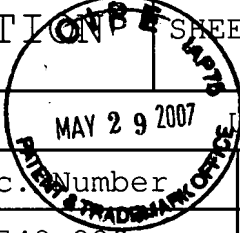
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DATE OF DEPOSIT: **May 29, 2007**

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PTO-1449		Page 1/1		U.S. Patent App No.10/593,932		KIYO-48	
INFORMATION DISCLOSURE CITATIONS				Inventor: Sasaki, Tatsuo			
				SHEET-LIKE FORMED MATERIAL		Group Art U: Unk	
 U.S. Patent Documents							
Exmr	Doc. Number	Date	Name	C	Sb	FD	
	6,748,229	11/2002	Epstein				
	6,667,092	12/2003	Brollier				
FOREIGN PATENT DOCUMENTS							
1.	Japan Patent Reference JP 2002-319006 of 2002/10/31 and entitled "ANTI-COUNTERFEIT THREAD, ANTI-COUNTERFEIT SHEET-SHAPED MATERIAL USING IT, AND METHOD OF MANUFACTURING IT"						
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